LN152 GaAs Infrared Light Emitting Diode

For optical control systems

Features

- High-power output, high-efficiency: $P_0 = 10 \text{ mW}$ (typ.)
- Wide directivity, matched for external optical systems: $\theta = 90^{\circ}$
- Infrared light emission close to monochromatic light: $\lambda_P = 950$ nm (typ.)
- Optimum for measuring instruments and control equipments in combination with silicon photodetectors
- High-speed modulation

Absolute Maximum Ratings $T_a = 25^{\circ}C$

Parameter	Symbol	Rating	Unit	
Power dissipation	P _D	160	mW	
Forward current	I _F	100	mA	
Pulse forward current *	I _{FP}	1.5	Α	
Reverse voltage	V _R	3	V	
Operating ambient temperature	T _{opr}	-25 to +85	°C	
Storage temperature	T _{stg}	-30 to +100	°C	

Note) *: f = 100 Hz, Duty cycle = 0.1%

Electro-Optical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Radiant power *	Po	$I_{\rm F} = 100 \mathrm{mA}$	5	100	7	mW
Reverse current	I _R	$V_R = 3 V$	J. L	ilo.	10	μΑ
Forward voltage	V _F	$I_{\rm F} = 100 \mathrm{mA}$	n ch	1.3	1.6	V
Terminal capacitance	Ct	$V_{\rm R} = 0 \text{ V}, \text{ f} = 1 \text{ MHz}$	OS/	60		pF
Peak emission wavelength	$\lambda_{\rm P}$	$I_{\rm F} = 100 \mathrm{mA}$		950		nm
Spectral half band width	Δλ	I _F = 100 mA		50		nm
Rise time	t _r	$I_{\rm FP} = 100 {\rm mA}$		1		μs
Fall time	t _f	$I_{\rm FP} = 100 \mathrm{mA}$		1		μs
Half-power angle	θ	The angle when the radiant power is halved.		90		0

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

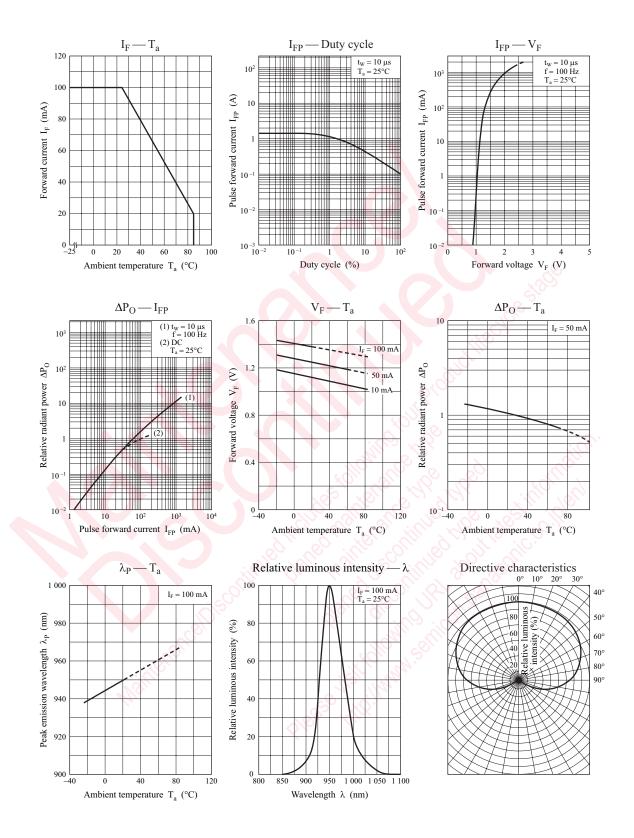
2. Cutoff frequency: 1 MHz

$$f_{C}: 10 \times \log \frac{P_{O} \text{ at } f = f_{C}}{P_{O} \text{ at } f = 50 \text{ kHz}} = -3$$

3. *: A light detection element uses a silicon diode have proofread a load with a standard device.

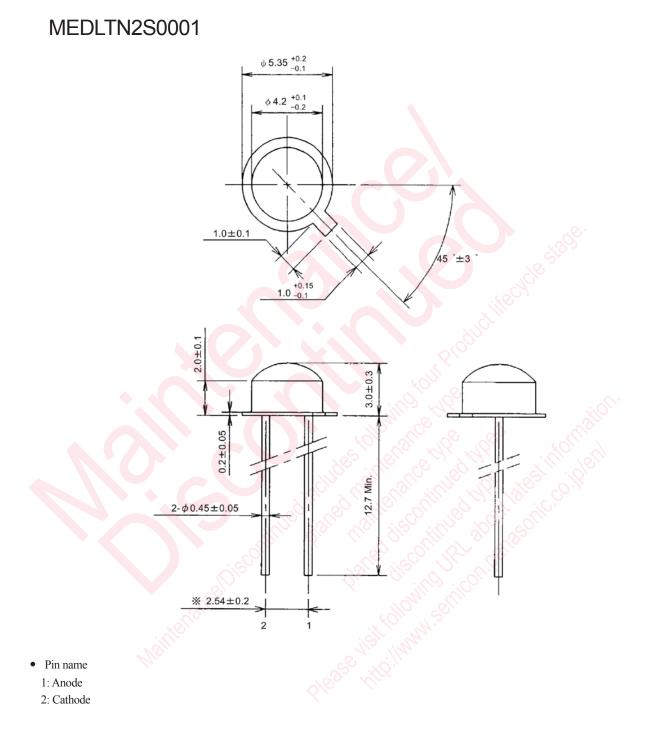
LN152

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Package (Unit: mm)



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